

ABSTRACT OF THE DISCLOSURE

An integrated circuit is provided having an alignment feature integral with the lead frame. The integrated circuit includes a lead frame coupled with a semiconductor die, and is partially encapsulated in insulating material. The lead frame has the alignment feature therein. The alignment feature includes a cut out on the lead frame taking the form of a semi-circle, protuberance, apertures, or slots. Alternatively, the alignment feature includes a removably coupled tab. After testing of the integrated circuit has been completed, the alignment tab is removed from the integrated circuit. The alignment feature can also be provided on a heat spreader which is attached to a side of or within the lead frame package.

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